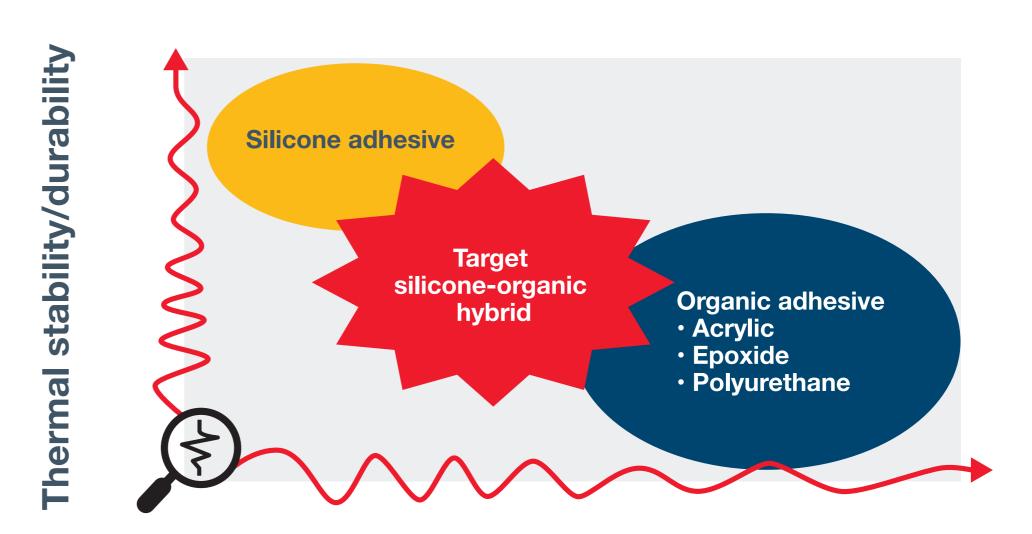


Novel silicone hybrid options for adhesives, molding & underfill

Underfill

- Enhance mechanical properties of silicones with excellent durability
- Non-yellowing for light module applications
- Tunable technology to fit applications



Mechanical strength/adhesion

Molding

Chip

Bonding

